

M5M418160BJ,TP-6,-7,-6S,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 1048576-word by 16-bit dynamic RAMS, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential.

The use of double-layer aluminum process combined with triple-well CMOS technology and a single-transistor dynamic storage stacked capacitor cell provide high circuit density at reduced costs. Multiplexed address inputs permit both a reduction in pins and an increase in system densities.

FEATURES

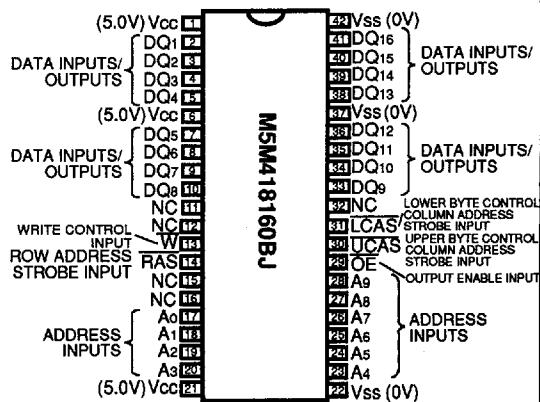
Type name	RAS access time (max.ns)	CAS access time (max.ns)	Address access time (max.ns)	OE access time (max.ns)	Cycle time (min.ns)	Power dissipation (typ.mW)
MSM418160BXX-6,-6S	60	15	30	15	110	680
MSM418160BXX-7,-7S	70	20	35	20	130	590

XX=J,TP

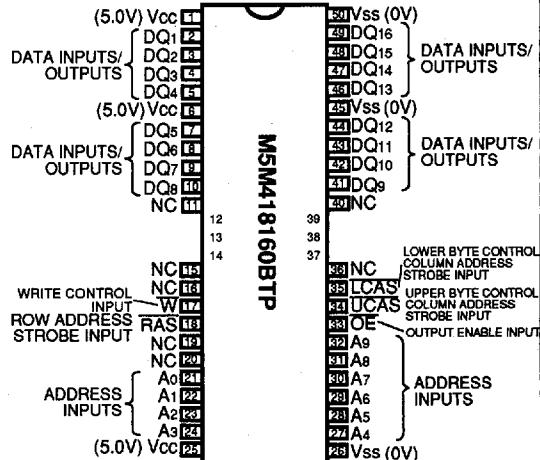
- Standard 42pin SOJ, 50pin TSOP
- Single 5.0V ± 10% supply
- Low stand-by power dissipation
5.5mW (Max) CMOS input level
- Low operating power dissipation
MSM418160Bxx -6, -6S 940.0mW (Max)
MSM418160Bxx -7, -7S 830.0mW (Max)
- Fast-page mode, Read-modify-write, RAS-only refresh, CAS before RAS refresh, Hidden refresh capabilities
- Early-write mode and OE to control output buffer impedance
- All inputs, output TTL compatible and low capacitance
- 1024 refresh cycles every 16.4ms (A0 ~A9)

APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

PIN CONFIGURATION (TOP VIEW)

Outline 42P0K(400mil SOJ)



Outline 50P3W-L(400mil TSOP)

NC : NO CONNECTION

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FUNCTION

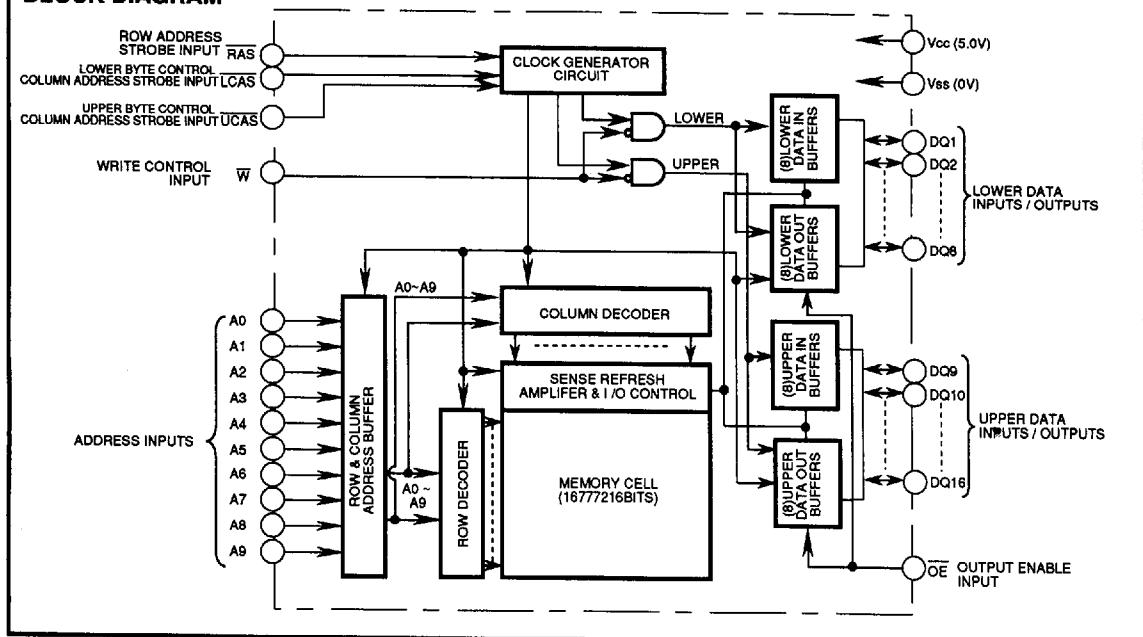
The M5M418160BJ,TP provide, in addition to normal read, write, and read-modify-write operations, a number of other

functions, e.g., fast page mode, RAS-only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs					Input/Output	
	RAS	LCAS	UCAS	W	OE	DQ1-DQ8	DQ9-DQ16
Lower byte Read	ACT	ACT	NAC	NAC	ACT	DOUT	OPN
Upper byte Read	ACT	NAC	ACT	NAC	ACT	OPN	DOUT
Word Read	ACT	ACT	ACT	NAC	ACT	DOUT	DOUT
Lower Byte Write	ACT	ACT	NAC	ACT	NAC	DIN	DNC
Upper Byte Write	ACT	NAC	ACT	ACT	NAC	DNC	DIN
Word write	ACT	ACT	ACT	ACT	NAC	DIN	DIN
RAS-only refresh	ACT	NAC	NAC	DNC	DNC	OPN	OPN
Lower Byte Hidden refresh	ACT	ACT	NAC	NAC	ACT	DOUT	OPN
Upper Byte Hidden refresh	ACT	NAC	ACT	NAC	ACT	OPN	DOUT
Hidden refresh	ACT	ACT	ACT	NAC	ACT	DOUT	DOUT
CAS before RAS refresh	ACT	ACT	ACT	DNC	DNC	OPN	OPN
Stand-by	NAC	DNC	DNC	DNC	DNC	OPN	OPN

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : invalid, APD : applied, OPN : open

BLOCK DIAGRAM

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{cc}	Supply voltage		-1~7	V
V _I	Input voltage	With respect to V _{ss}	-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a =25°C	1000	mW
T _{opr}	Operating temperature		0~70	°C
T _{stg}	Storage temperature		-65~150	°C

RECOMMENDED OPERATING CONDITIONS (T_a=0~70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{cc}	Supply voltage	4.5	5.0	5.5	V
V _{ss}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.0	V
V _{IL}	Low-level input voltage, all inputs	-1		0.8	V

Note 1 : All voltage values are with respect to V_{ss}.ELECTRICAL CHARACTERISTICS (T_a=0~70°C, V_{cc}=5.0V ±10%, V_{ss}=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{OH}	High-level output voltage	I _{OH} =-5mA	2.4		V _{cc}	V
V _{OL}	Low-level output voltage	I _{OL} =4.2mA	0		0.4	V
I _{OZ}	Off-state output current	Q floating, 0V ≤ V _{out} ≤ 5.5V	-10		10	μA
I _I	Input current	0V ≤ V _{IN} ≤ 6V, Other inputs pins=0V	-10		10	μA
I _{CC1(AV)}	Average supply current from V _{cc} operating (Note 3,4,5)	M5M418160B-6,-6S RAS, CAS cycling t _{RC} =t _{WR} =min. output open			170	mA
		M5M418160B-7,-7S			150	
I _{CC2}	Supply current from V _{cc} , stand-by (Note 6)	M5M418160B-6,-7 RAS= CAS = V _{IH} , output open			2	mA
		M5M418160B-6S,-7S RAS= CAS ≥ V _{cc} -0.2V, output open			1	
I _{CC3} (AV)	Average supply current from V _{cc} refreshing (Note 3,5)	M5M418160B-6,-6S RAS cycling, CAS= V _{IH} t _{RC} =min. output open			0.3	mA
		M5M418160B-7,-7S			170	
I _{CC4(AV)}	Average supply current from V _{cc} Fast-Page-Mode (Note 3,4,5)	M5M418160B-6,-6S RAS= V _{IL} , CAS cycling t _{RC} =min. output open			85	mA
		M5M418160B-7,-7S			75	
I _{CC6(AV)}	Average supply current from V _{cc} CAS before RAS refresh mode (Note 3)	M5M418160B-6,-6S CAS before RAS refresh cycling t _{RC} =min. output open			170	mA
		M5M418160B-7,-7S			150	

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{CC1(AV)}, I_{CC3(AV)} and I_{CC4(AV)} are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.4: I_{CC1(AV)} and I_{CC4(AV)} are dependent on output loading. Specified values are obtained with the output open.5: Column Address can be changed once or less while RAS=V_{IL} and LCAS/UCAS=V_{IH}.CAPACITANCE (T_a=0~70°C, V_{cc}=5.0V ±10%, V_{ss}=0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _{i(A)}	Input capacitance, address inputs				5	pF
C _{i(OE)}	Input capacitance, OE input				7	pF
C _{i(W)}	Input capacitance, W input				7	pF
C _{i(RAS)}	Input capacitance, RAS input				7	pF
C _{i(CAS)}	Input capacitance, CAS input				7	pF
C _{i/o}	Input/Output capacitance, data ports				8	pF

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SWITCHING CHARACTERISTICS (Ta=0 ~ 70°C, Vcc=5.0V ± 10%, Vss=0V, unless otherwise noted, see notes 6,13,14)

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
t _{CAC}	Access time from CAS	(Note7,8)		15		20 ns	
t _{RAC}	Access time from RAS	(Note7,9)		60		70 ns	
t _{AA}	Column address access time	(Note 7,10)		30		35 ns	
t _{CPO}	Access time from CAS precharge	(Note 7,11)		35		40 ns	
t _{OEA}	Access time from OE	(Note 7)		15		20 ns	
t _{CLZ}	Output low impedance time from CAS low	(Note 7)	5		5	ns	
t _{OFF}	Output disable time after CAS high	(Note 12)	0	15	0	15 ns	
t _{OEZ}	Output disable time after OE high	(Note 12)	0	15	0	15 ns	

Note 6: An initial pause of 500 µs is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS clock such as RAS-Only refresh).

Note the RAS may be cycled during the initial pause. And any 8 RAS or RAS/CAS cycles are required after prolonged periods (greater than 16.4 ms) of RAS inactivity before proper device operation is achieved.

7: Measured with a load circuit equivalent to 100pF, VOH=2.4V(IOL=5mA) and VOL=0.4V(IOL=4.2mA).

8: Assumes that t_{RCO} ≥ t_{RCO(max)} and t_{ASC} ≥ t_{ASC(max)}.

9: Assumes that t_{RCO} ≤ t_{RCO(max)} and t_{RAD} ≥ t_{RAD(max)}. If t_{RCO} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RCAC} will increase by amount that t_{RCO} exceeds the value shown.

10: Assumes that t_{RAD} ≥ t_{RAD(max)} and t_{ASC} ≤ t_{ASC(max)}.

11: Assumes that t_{CPO} ≤ t_{CPO(max)} and t_{ASC} ≥ t_{ASC(max)}.

12: t_{OFF(max)} and t_{OEZ(max)} defines the time at which the output achieves the high impedance state (I_{out} = 10 µA) and is not reference to VOH(min) or VOL(max).

TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write ,Refresh, and Fast-Page Mode Cycles)

(Ta=0 ~ 70°C, Vcc=5.0V ± 10%, Vss=0V, unless otherwise noted, see notes 13,14)

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
t _{REF}	Refresh cycle time	-6, -7		16.4		16.4 ms	
t _{REF}	Refresh cycle time	-6S, -7S		128		128 ms	
t _{RP}	RAS high pulse width		40		50	ns	
t _{RCD}	Delay time, RAS low to CAS low	(Note15)	20	45	20	50 ns	
t _{CRP}	Delay time, CAS high to RAS low		10		10	ns	
t _{RPC}	Delay time, RAS high to CAS low		0		0	ns	
t _{CPO}	CAS high pulse width		10		10	ns	
t _{RAD}	Column address delay time from RAS low	(Note16)	15	30	15	35 ns	
t _{ASR}	Row address setup time before RAS low		0		0	ns	
t _{AASC}	Column address setup time before CAS low	(Note17)	0	10	0	10 ns	
t _{RAH}	Row address hold time after RAS low		10		10	ns	
t _{CAH}	Column address hold time after CAS low		15		15	ns	
t _{DZC}	Delay time, data to CAS low	(Note18)	0		0	ns	
t _{DZO}	Delay time, data to OE low	(Note18)	0		0	ns	
t _{DCD}	Delay time, CAS high to data	(Note19)	15		15	ns	
t _{DOB}	Delay time, OE high to data	(Note19)	15		15	ns	
t _r	Transition time	(Note20)	1	50	1	50 ns	

Note 13: The timing requirements are assumed tr = 5ns.

14: V_{IH(min)} and V_{IL(max)} are reference levels for measuring timing of input signals.

15: t_{RCD(max)} is specified as a reference point only. If t_{RCO} is less than t_{RCD(max)}, access time is t_{RAC}. If t_{RCD} is greater than t_{RCD(max)}, access time is controlled exclusively by t_{AA}. t_{RCD(min)} is specified as t_{RCD(min)}=t_{RAH(min)}+2T+1ASC(min).

16: t_{RAD(max)} is specified as a reference point only. If t_{RAD} ≥ t_{RAD(max)} and t_{ASC} ≤ t_{ASC(max)}, access time is controlled exclusively by t_{AA}.

17: t_{AASC(max)} is specified as a reference point only. If t_{RCO} ≥ t_{RCD(max)} and t_{ASC} ≥ t_{AASC(max)}, access time is controlled exclusively by t_{AA}.

18: Either t_{DZC} or t_{DZO} must be satisfied.

19: Either t_{DCD} or t_{DOB} must be satisfied.

20: t_r is measured between V_{IH(min)} and V_{IL(max)}.

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Read and Refresh Cycles

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
t _{RC}	Read cycle time	110		130		ns	
t _{RAS}	RAS low pulse width	60	10000	70	10000	ns	
t _{CAS}	CAS low pulse width	15	10000	20	10000	ns	
t _{CASH}	CAS hold time after RAS low	60		70		ns	
t _{RSH}	RAS hold time after CAS low	15		20		ns	
t _{RCSS}	Read Setup time before CAS low	0		0		ns	
t _{RCH}	Read hold time after CAS high	(Note 21)	0	0		ns	
t _{RHH}	Read hold time after RAS high	(Note 21)	10	10		ns	
t _{RAL}	Column address to RAS hold time	30		35		ns	
t _{COH}	CAS hold time after OE low	15		20		ns	
t _{RH}	RAS hold time after OE low	15		20		ns	

Note 21: Either t_{RCH} or t_{RHH} must be satisfied for a read cycle.**Write Cycle (Early Write and Delayed Write)**

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
t _{WC}	Write cycle time	110		130		ns	
t _{RAS}	RAS low pulse width	60	10000	70	10000	ns	
t _{CAS}	CAS low pulse width	15	10000	20	10000	ns	
t _{CASH}	CAS hold time after RAS low	60		70		ns	
t _{RSH}	RAS hold time after CAS low	15		20		ns	
t _{WCS}	Write setup time before CAS low	(Note 23)	0	0		ns	
t _{WCH}	Write hold time after CAS low		10	10		ns	
t _{CWL}	CAS hold time after W low		15	20		ns	
t _{RWL}	RAS hold time after W low		15	20		ns	
t _{WP}	Write pulse width		10	10		ns	
t _{DS}	Data setup time before CAS low or W low		0	0		ns	
t _{DH}	Data hold time after CAS low or W low		10	15		ns	
t _{OEH}	OE hold time after W low		15	20		ns	

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FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
tRWC	Read write/read modify write cycle time (Note22)	155		180		ns	
tRAS	RAS low pulse width	105	10000	120	10000	ns	
tCAS	CAS low pulse width	60	10000	70	10000	ns	
tCSH	CAS hold time after RAS low	105		120		ns	
tRSH	RAS hold time after CAS low	60		70		ns	
tRCS	Read setup time before CAS low	0		0		ns	
tCWD	Delay time, CAS low to W low (Note23)	40		45		ns	
tRWL	Delay time, RAS low to W low (Note23)	85		95		ns	
tAWD	Delay time, address to W low (Note23)	55		60		ns	
tCWL	CAS hold time after W low	15		20		ns	
tRWL	RAS hold time after W low	15		20		ns	
tWP	Write pulse width	10		10		ns	
tDS	Data setup time before W low	0		0		ns	
tDH	Data hold time after W low	10		15		ns	
tOEH	OE hold time after W low	15		15		ns	

Note 22: tRWC is specified as $tRWC(\min)=tRAC(\max)+tODD(\min)+tRWL(\min)+tRP(\min)+5\text{tr}$.

23: twcs, tcwd, trwd and tawd and, tcpwd are specified as reference points only. If $tWCS \geq tWCS(\min)$ the cycle is an early write cycle and the DQ pins will remain high impedance throughout the entire cycle. If $tCWD \geq tCWD(\min)$, $tRWD \geq tRWD(\min)$, $tAWD \geq tAWD(\min)$ and $tCPWD \geq tCPWD(\min)$ (for fast page mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address. If neither of the above condition (delayed write) of the DQ (at access time and until CAS or OE goes back to V_{IH}) is indeterminate.

Fast-Page Mode Cycle (Read, Early Write, Read -Write, Read-Modify-Write Cycle) (Note 24)

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
tPC	Fast page mode read/write cycle time	40		45		ns	
tPRWC	Fast page mode read write/read modify write cycle time	85		95		ns	
tRAS	RAS low pulse width for read write cycle (Note25)	100	125000	115	125000	ns	
tCP	CAS high pulse width (Note26)	10	15	10	15	ns	
tCPRH	RAS hold time after CAS precharge	35		40		ns	
tCPWD	Delay time, CAS precharge to W low (Note23)	60		65		ns	

Note 24: All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

25: tRAS(min) is specified as two cycles of CAS input are performed.

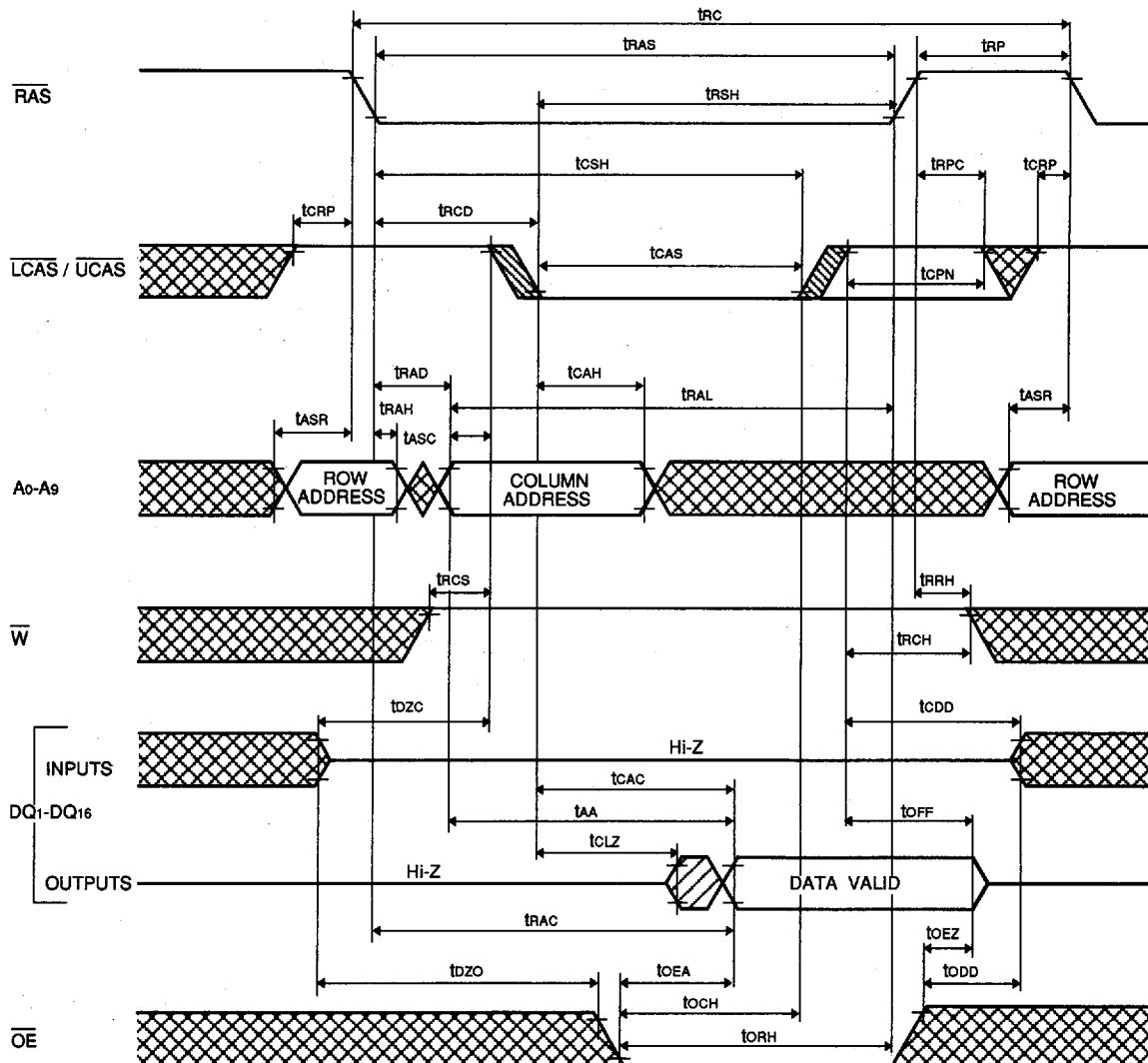
26: tCP(max) is specified as a reference point only.

CAS before RAS Refresh Cycle (Note 27)

Symbol	Parameter	Limits				Unit	
		M5M418160B-6,-6S		M5M418160B-7,-7S			
		Min	Max	Min	Max		
tCSR	CAS setup time before RAS low	10		10		ns	
tCHR	CAS hold time after RAS low	10		15		ns	

Note 27: Eight or more CAS before RAS cycles instead of eight RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

Timing Diagrams (Note 28)
Read Cycle



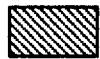
Note 28



Indicates the don't care input.
 $V_{IH(\min.)} \leq V_{IN} \leq V_{IH(\max.)}$ or $V_{IL(\min.)} \leq V_{IN} \leq V_{IL(\max.)}$



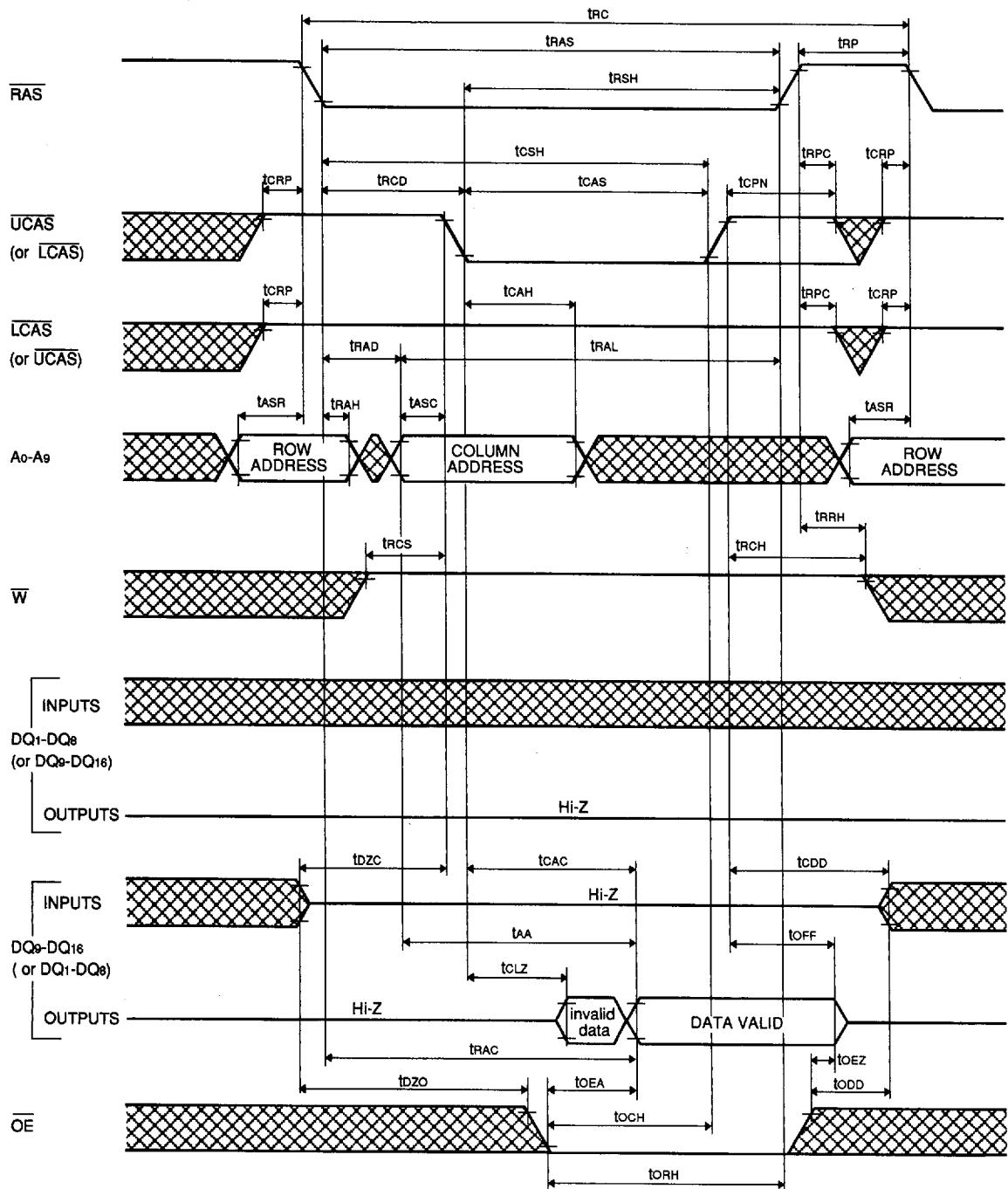
Indicates the invalid output.



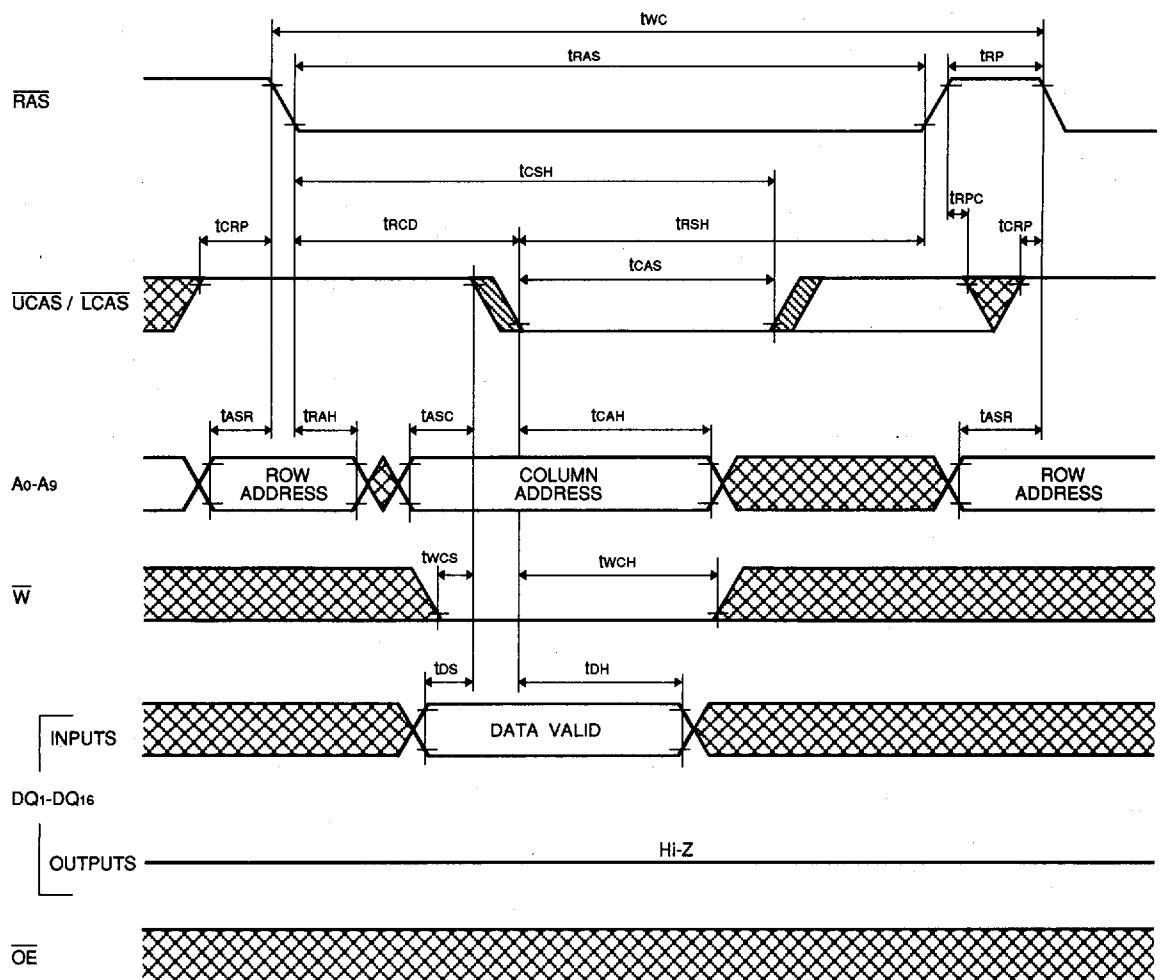
Indicates the skew of the two inputs.

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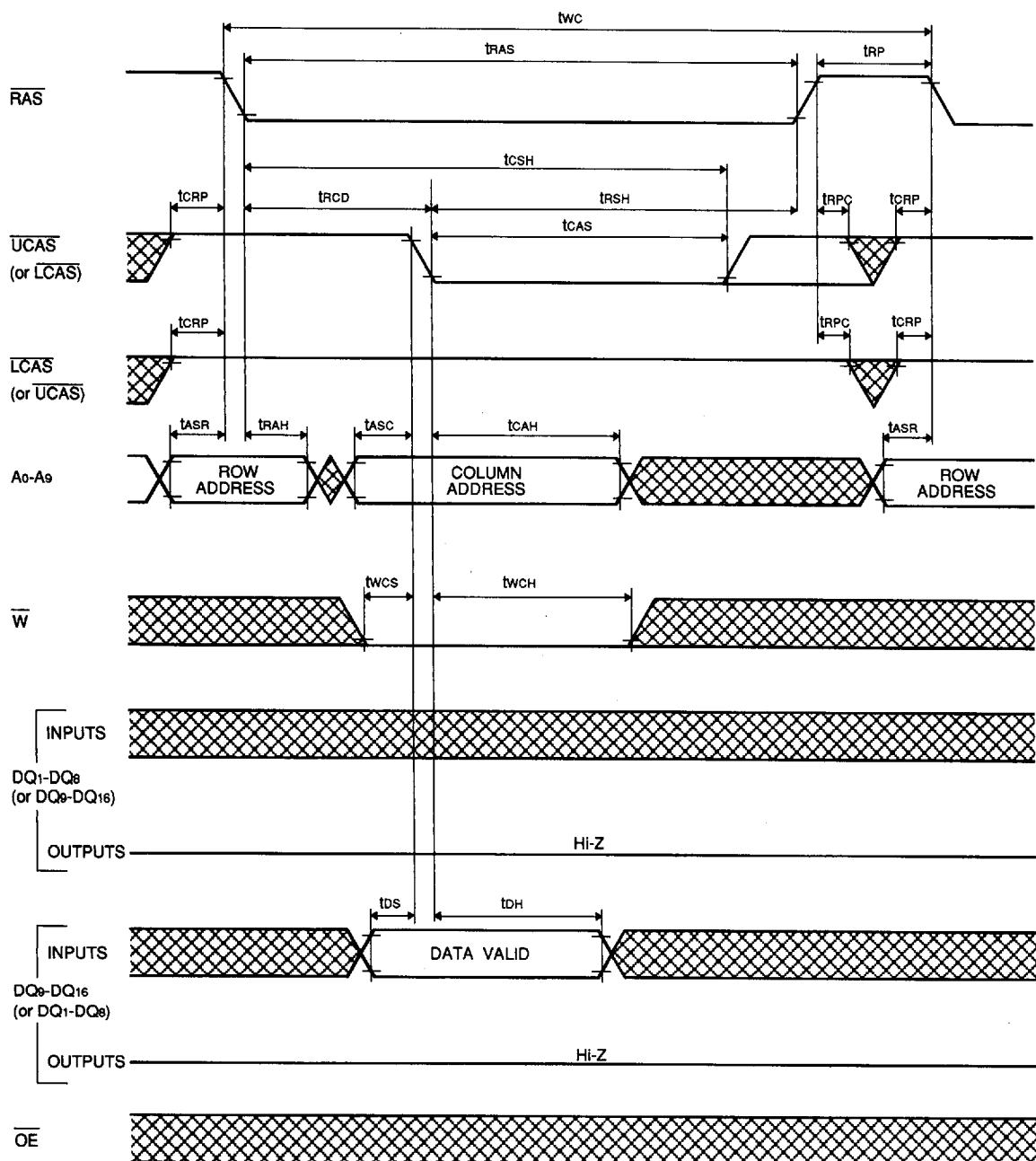
Upper / (Lower) Byte Read Cycle



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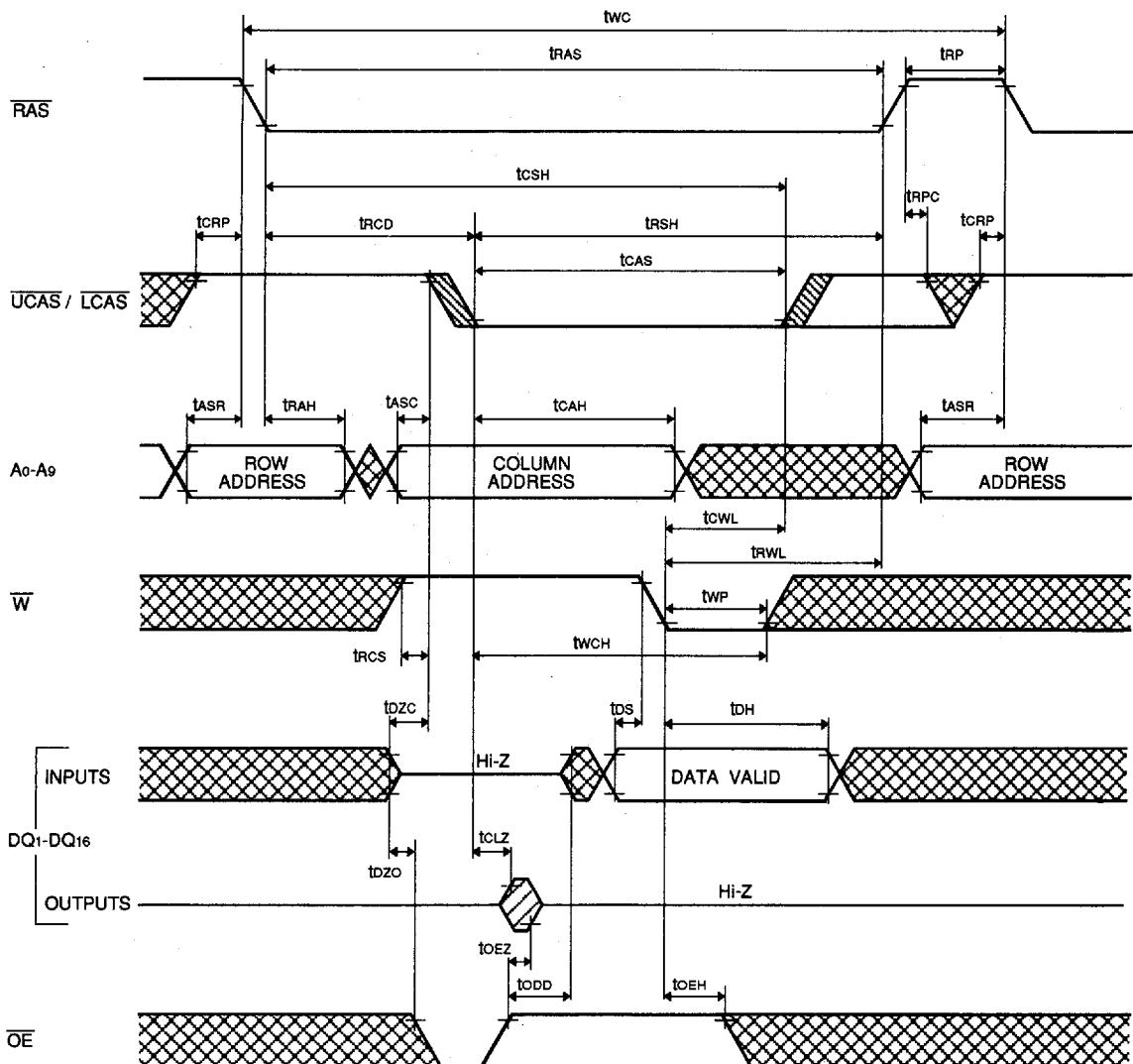
Write Cycle (Early write)

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Upper/(Lower) Byte Write Cycle (Early write)

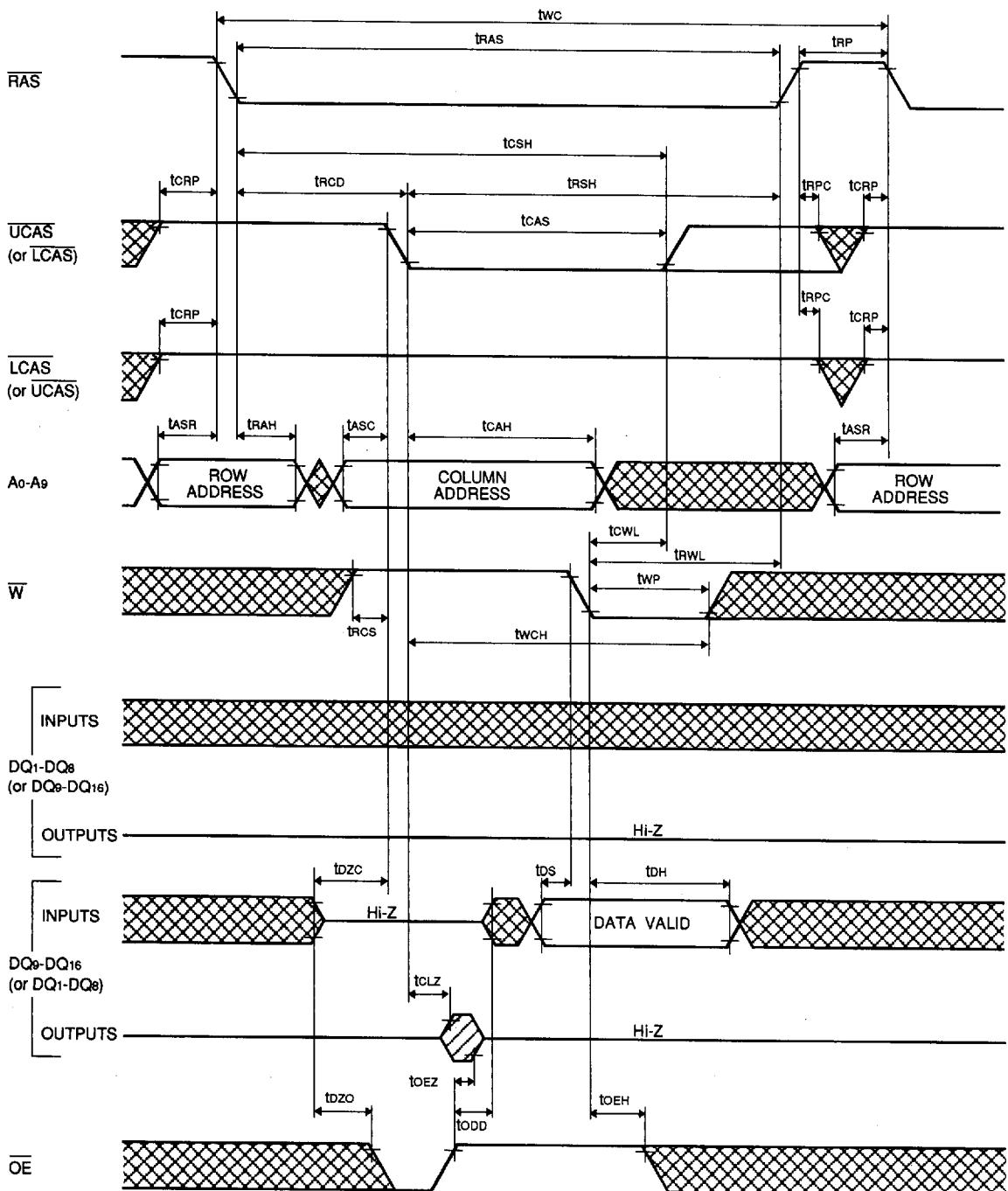
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Write Cycle (Delayed write)

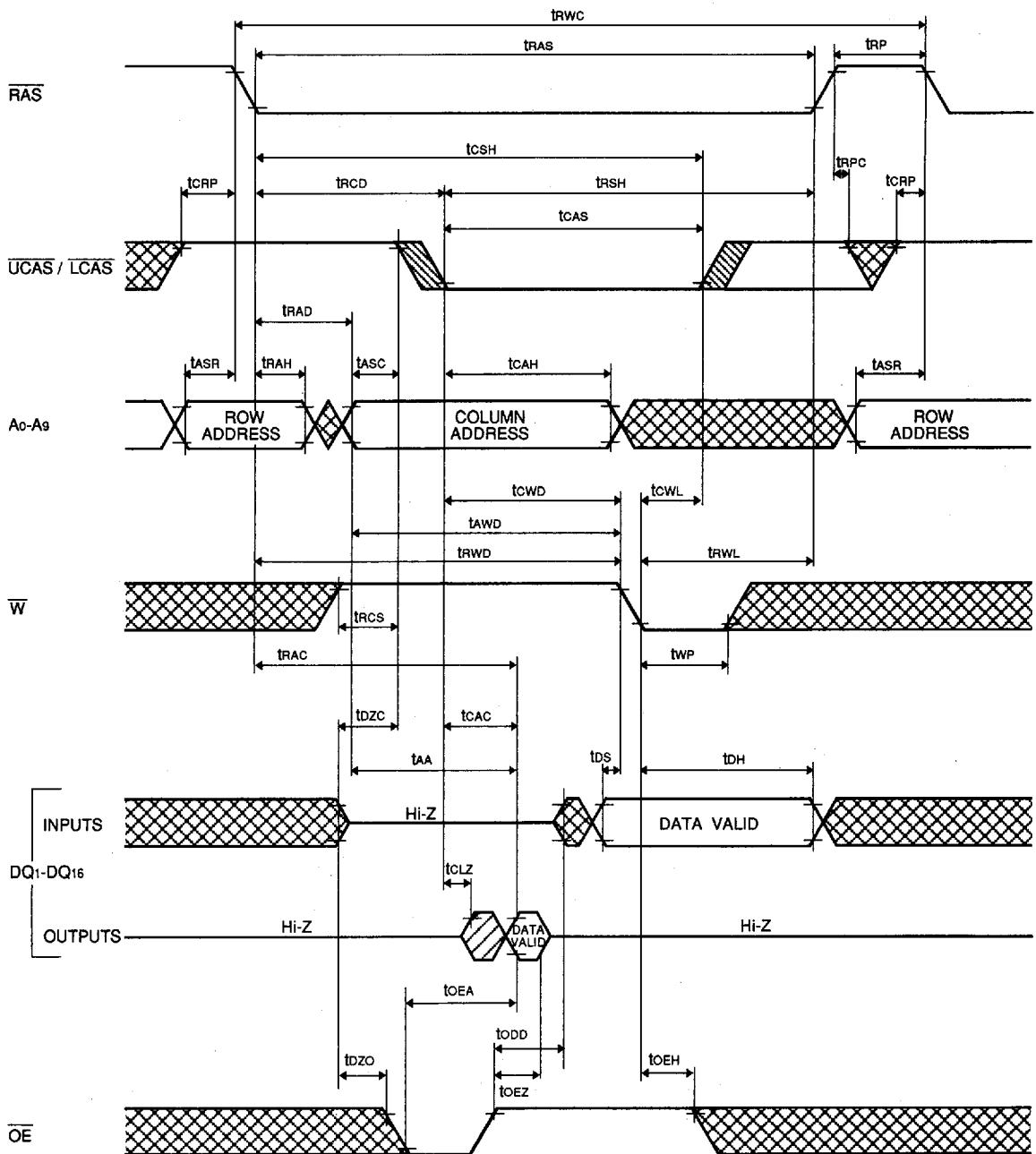


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Upper/(Lower) Byte Write Cycle (Delayed write)

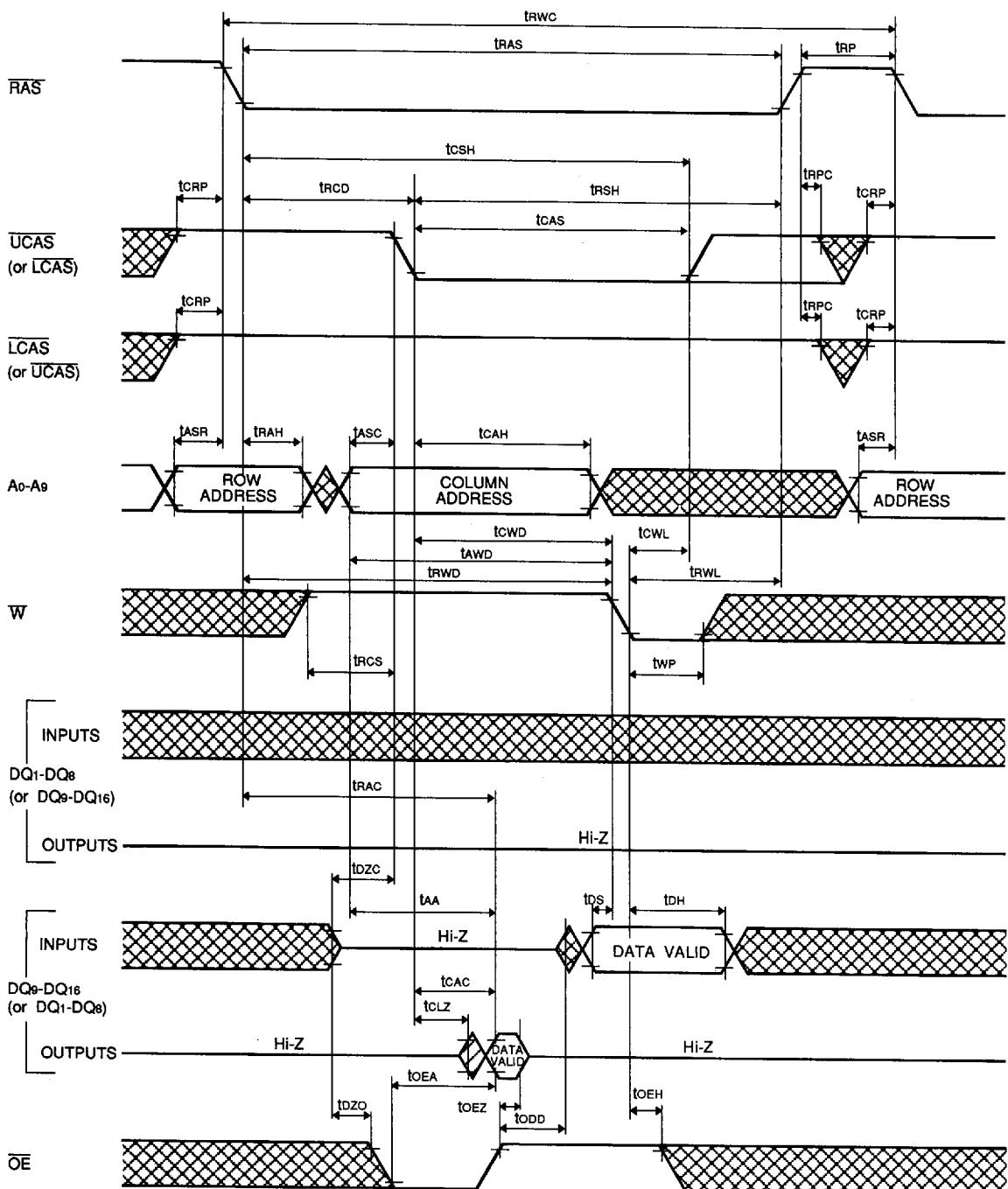


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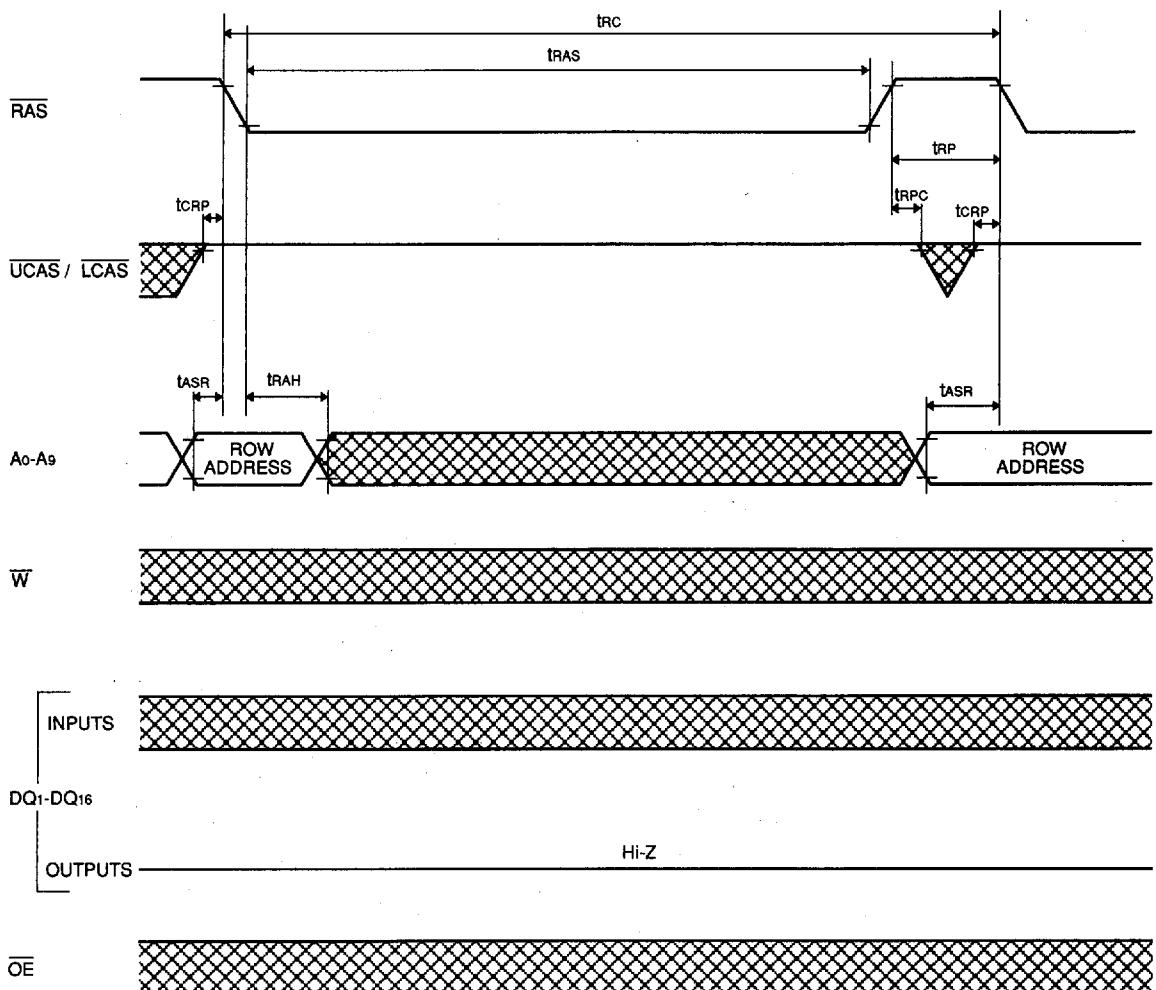
Read-Write, Read-Modify-Write Cycle

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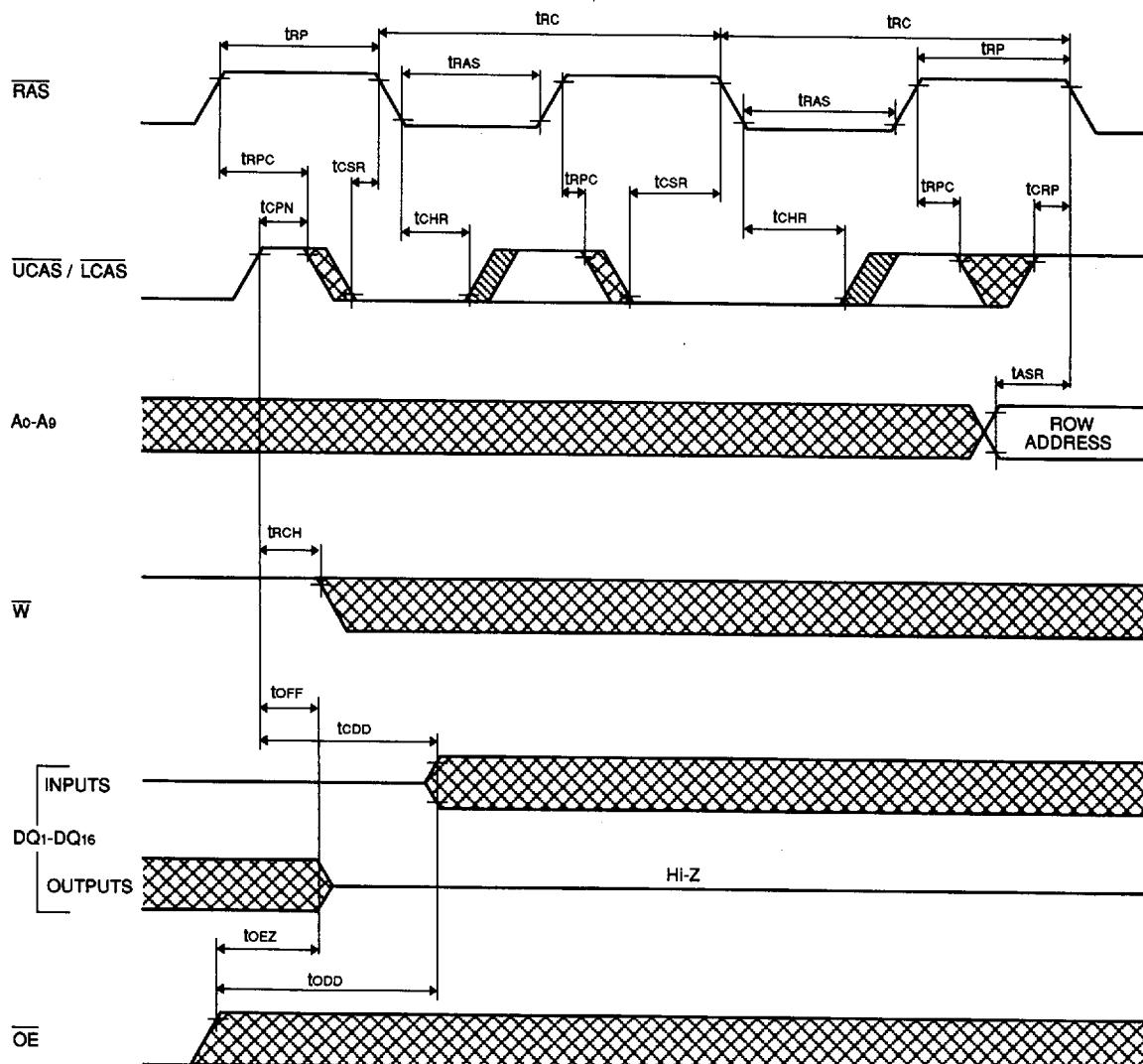
Read-Upper/(Lower) Write, Read-Modify-Upper/(Lower) Write Cycle



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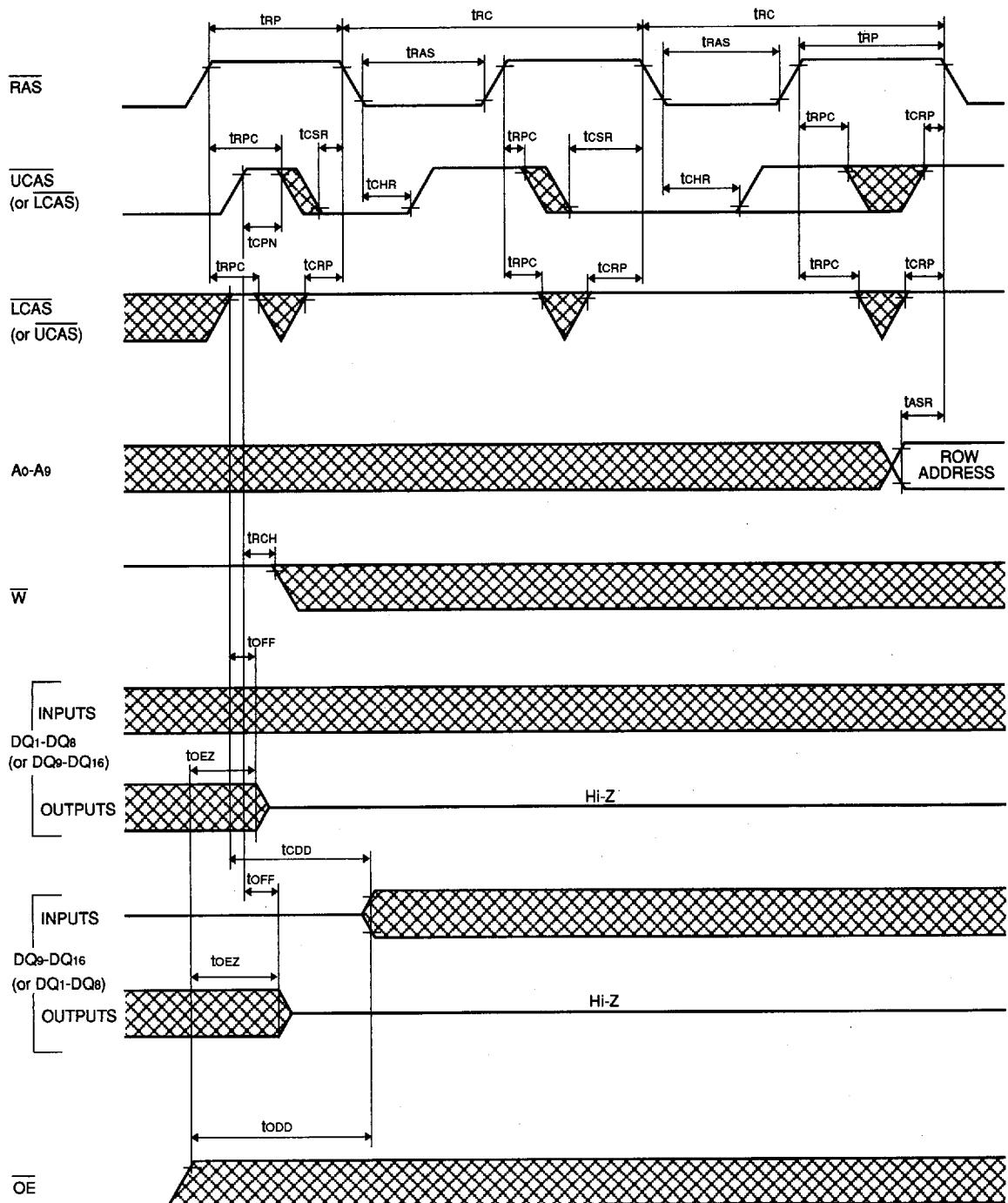
RAS-only Refresh Cycle

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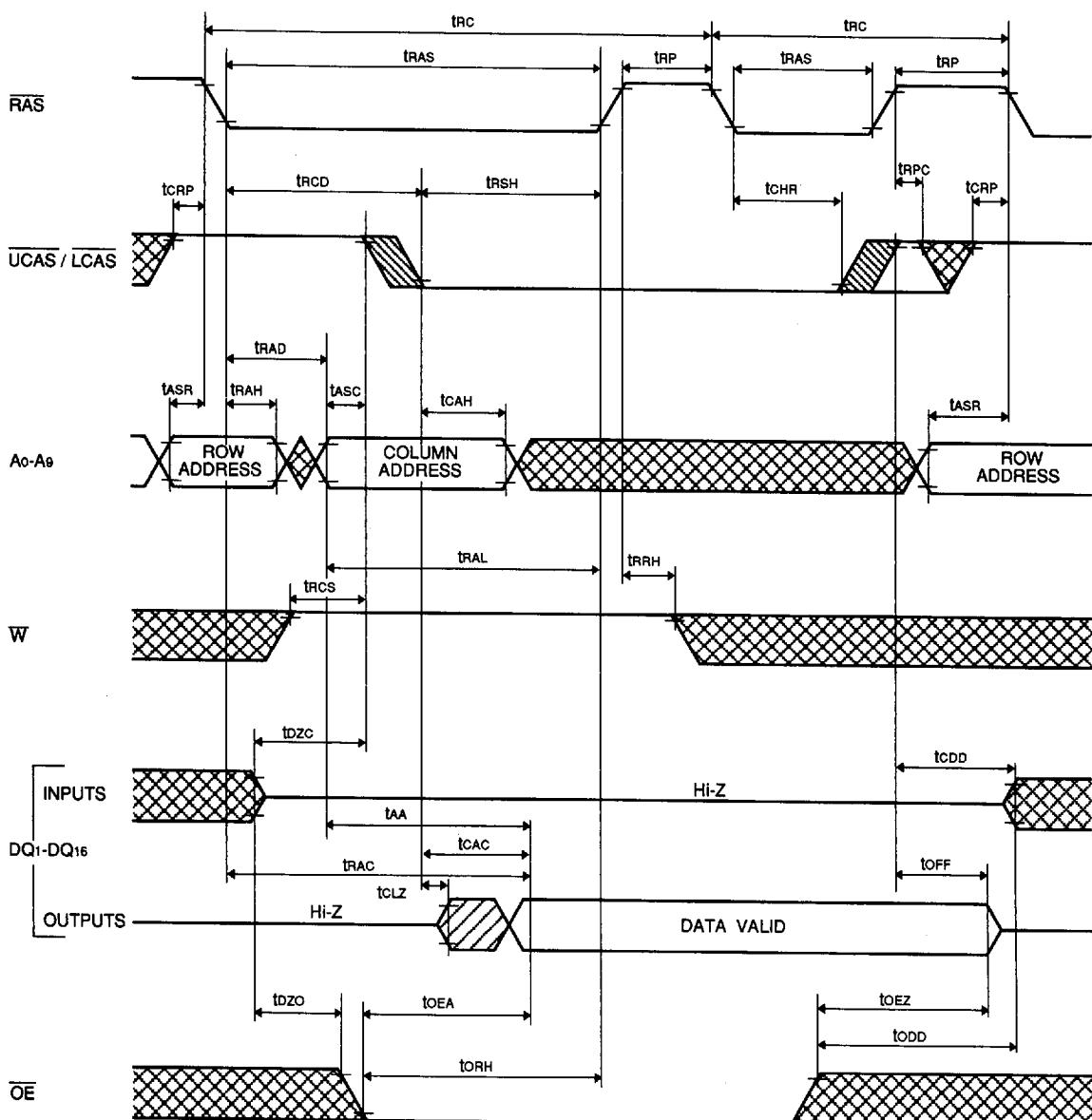
CAS before RAS Refresh Cycle

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Upper/(Lower) CAS before RAS Refresh Cycle



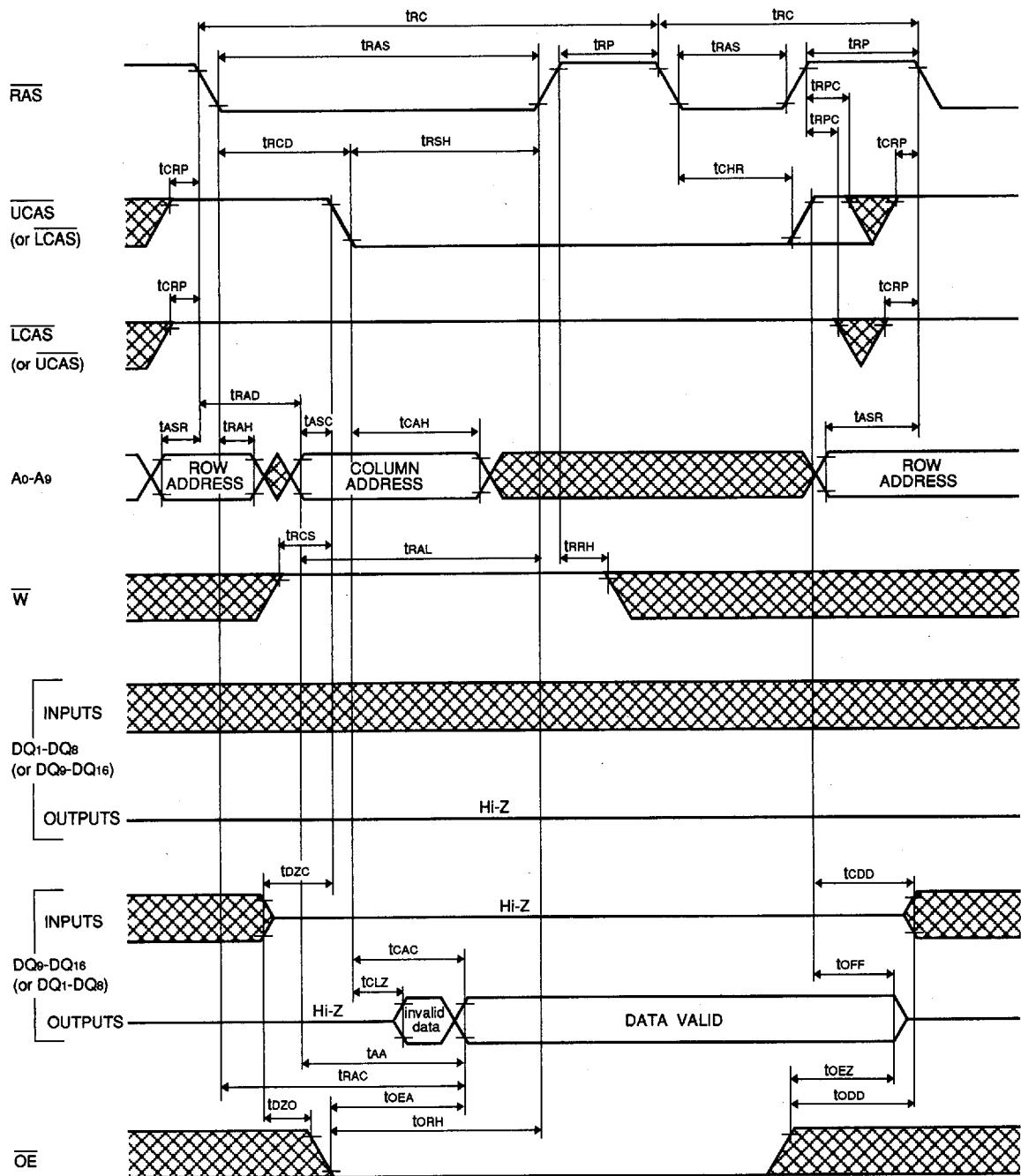
Hidden Refresh Cycle (Read) (Note 29)



Note 29: Early write, delayed write, read write or read modify write cycle is applicable as well as read cycle.
 Timing requirements and output state are the same as that of each cycle shown above.

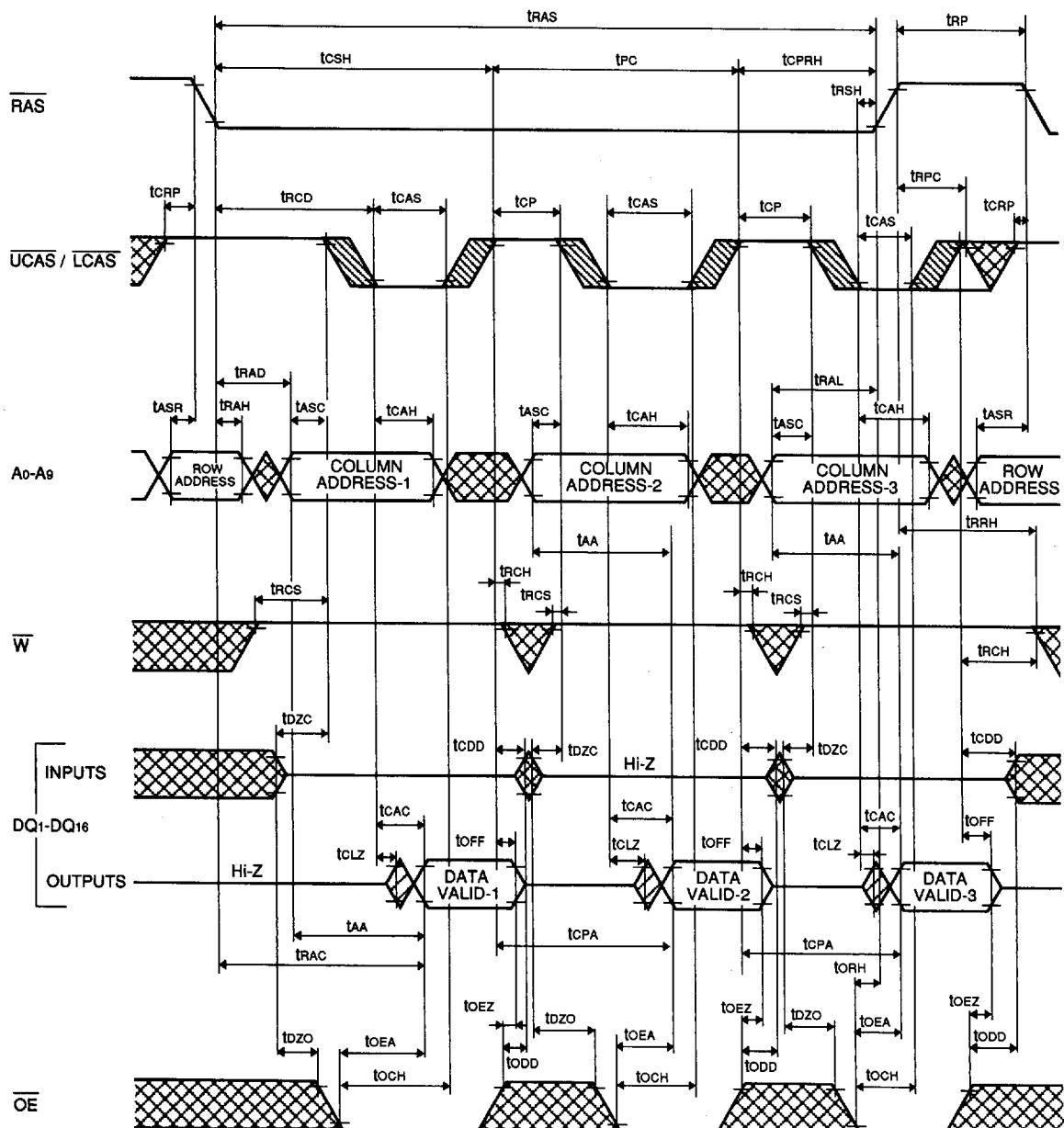
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Upper/(Lower) Hidden Refresh Cycle (Byte Read) (Note 29)



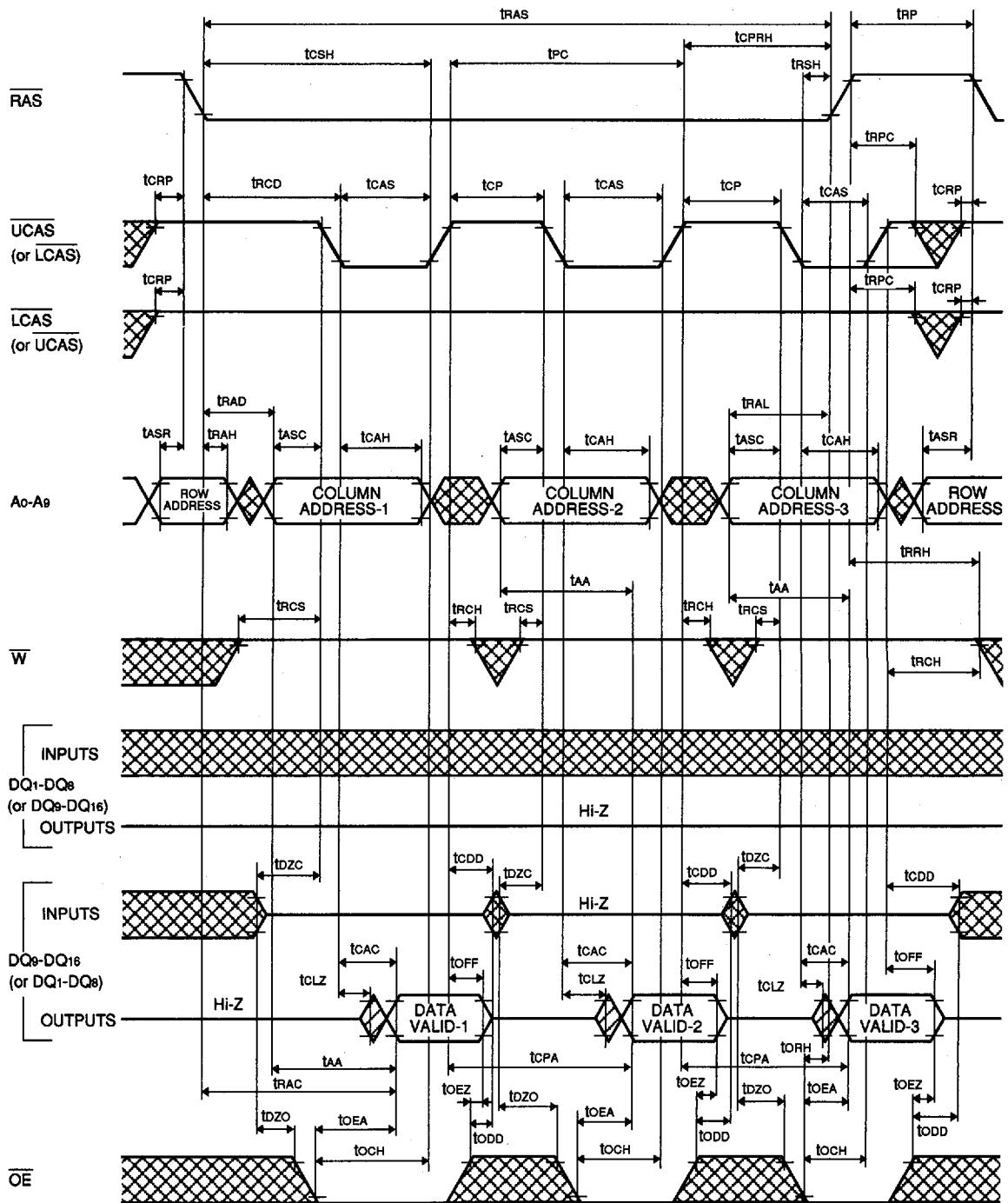
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Fast Page Mode Read Cycle

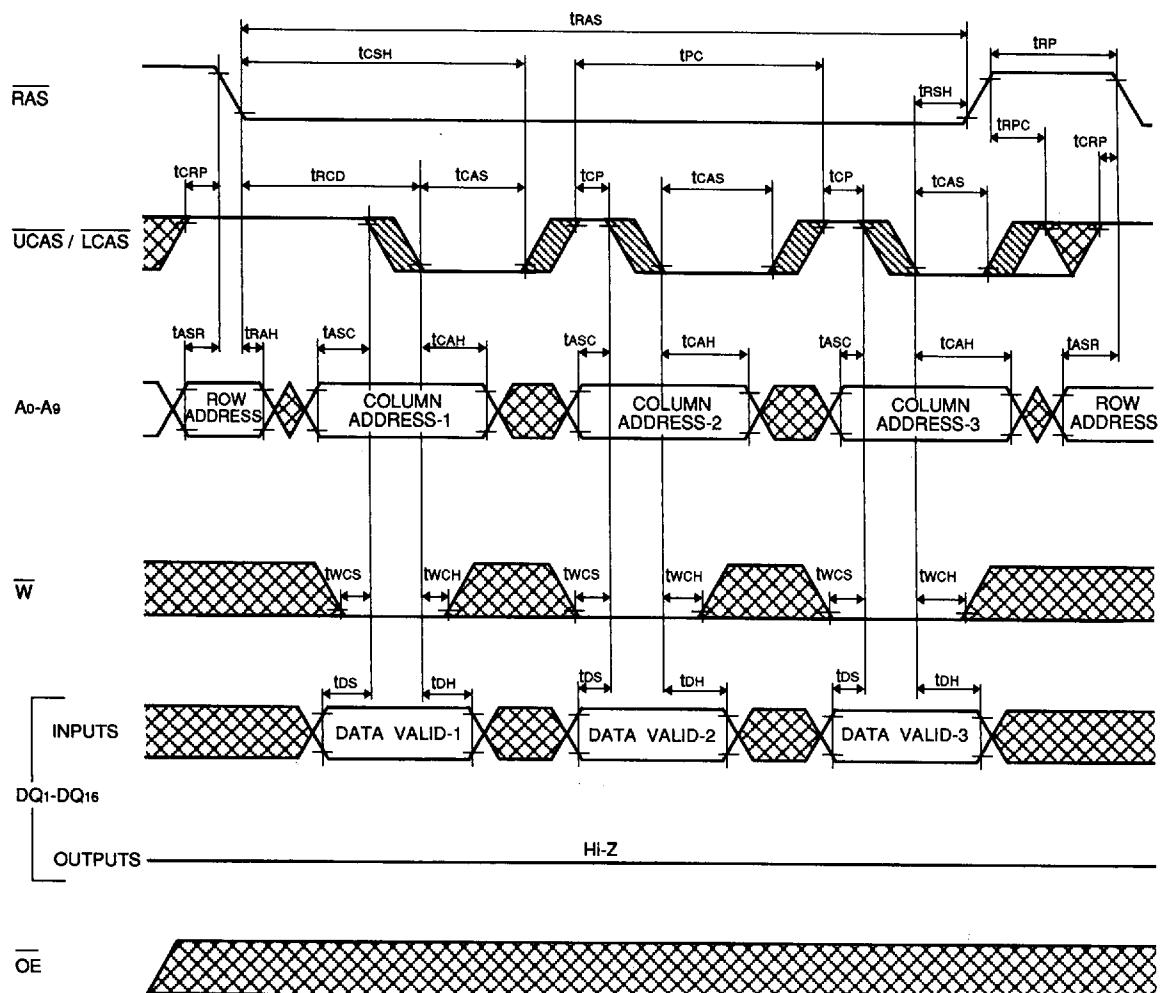


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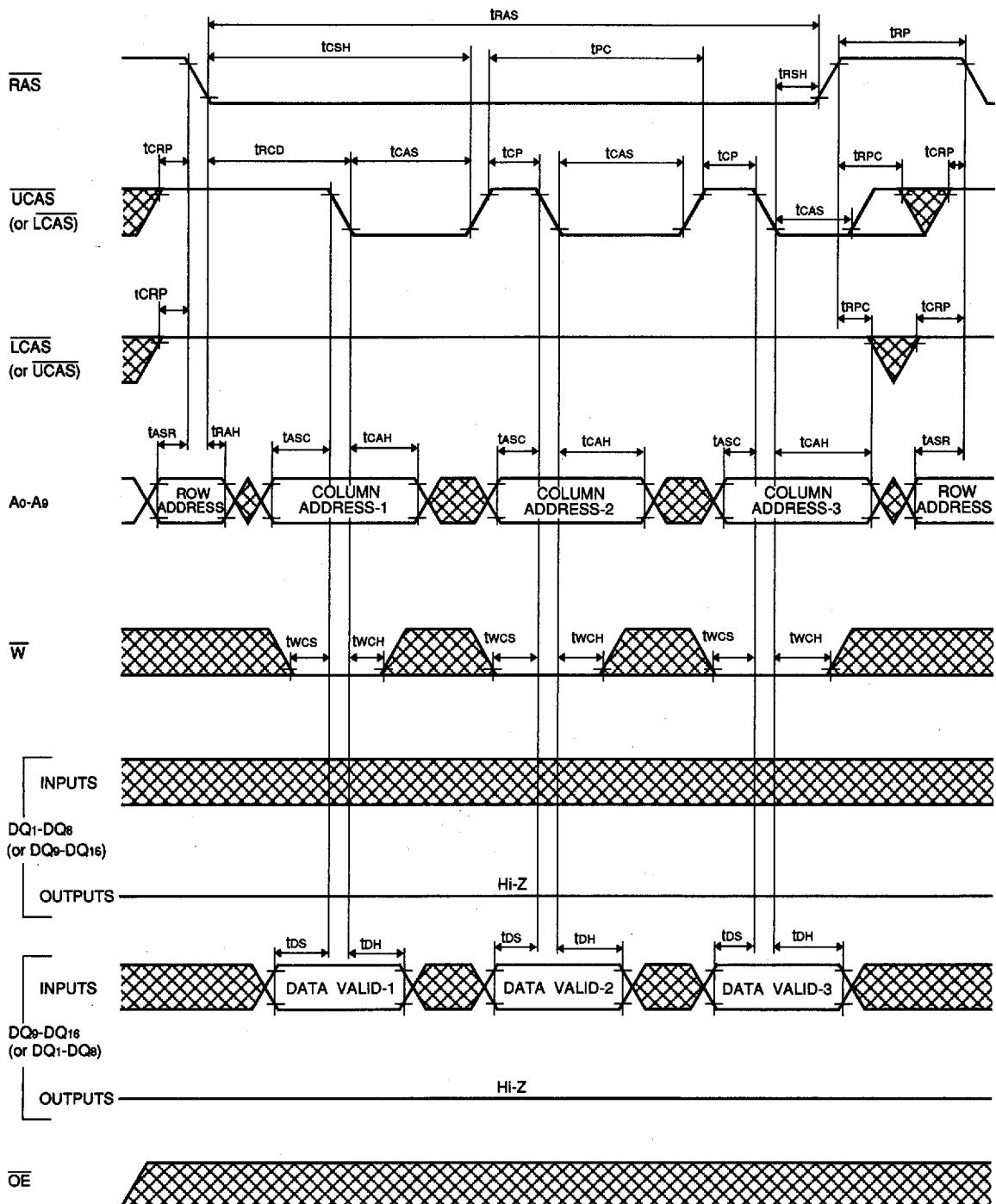
Upper/(Lower) Fast Page Mode Read Cycle



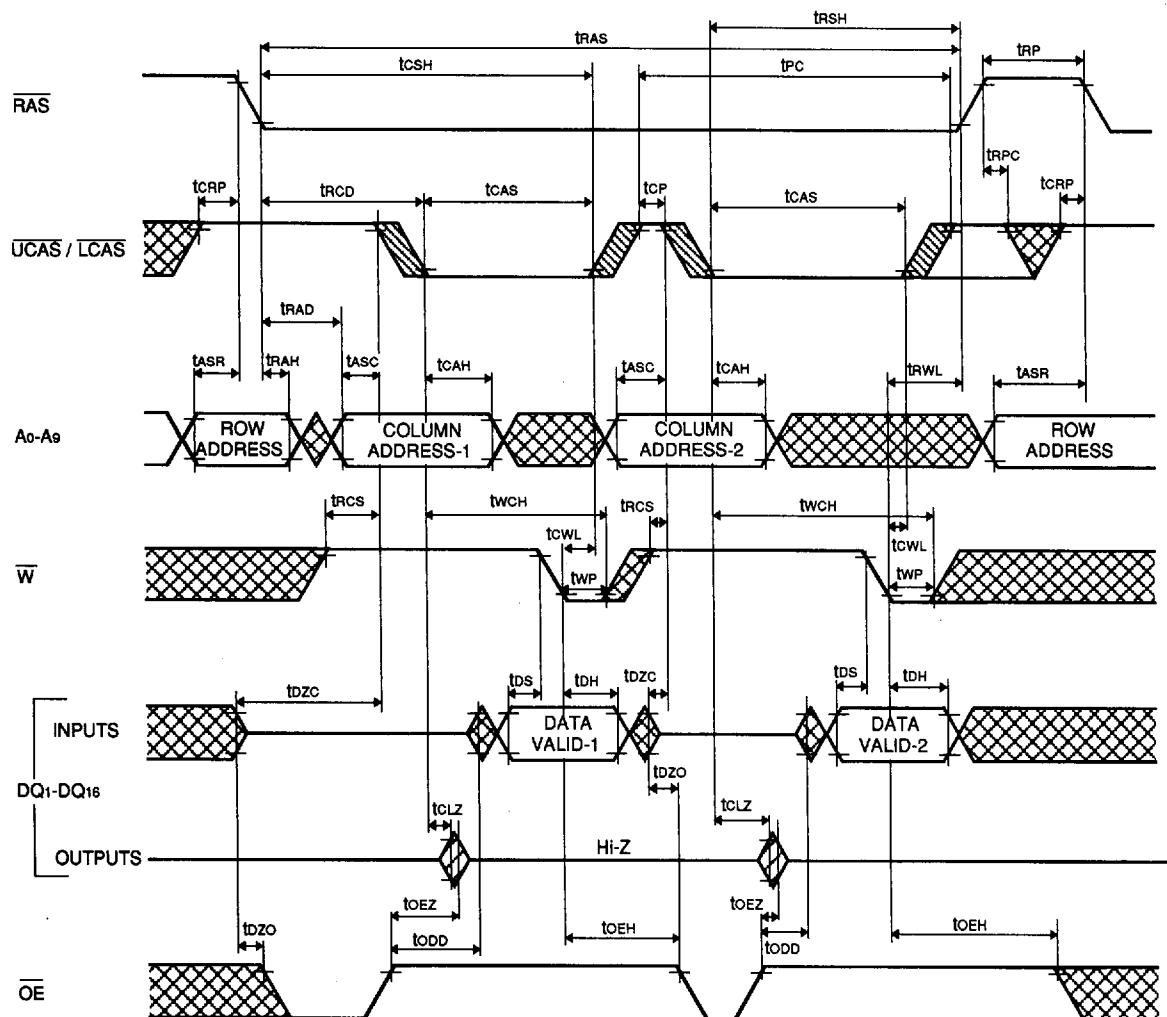
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Fast Page Mode Write Cycle (Early Write)

Fast Page Mode Upper/(Lower) Byte Write Cycle (Early Write)

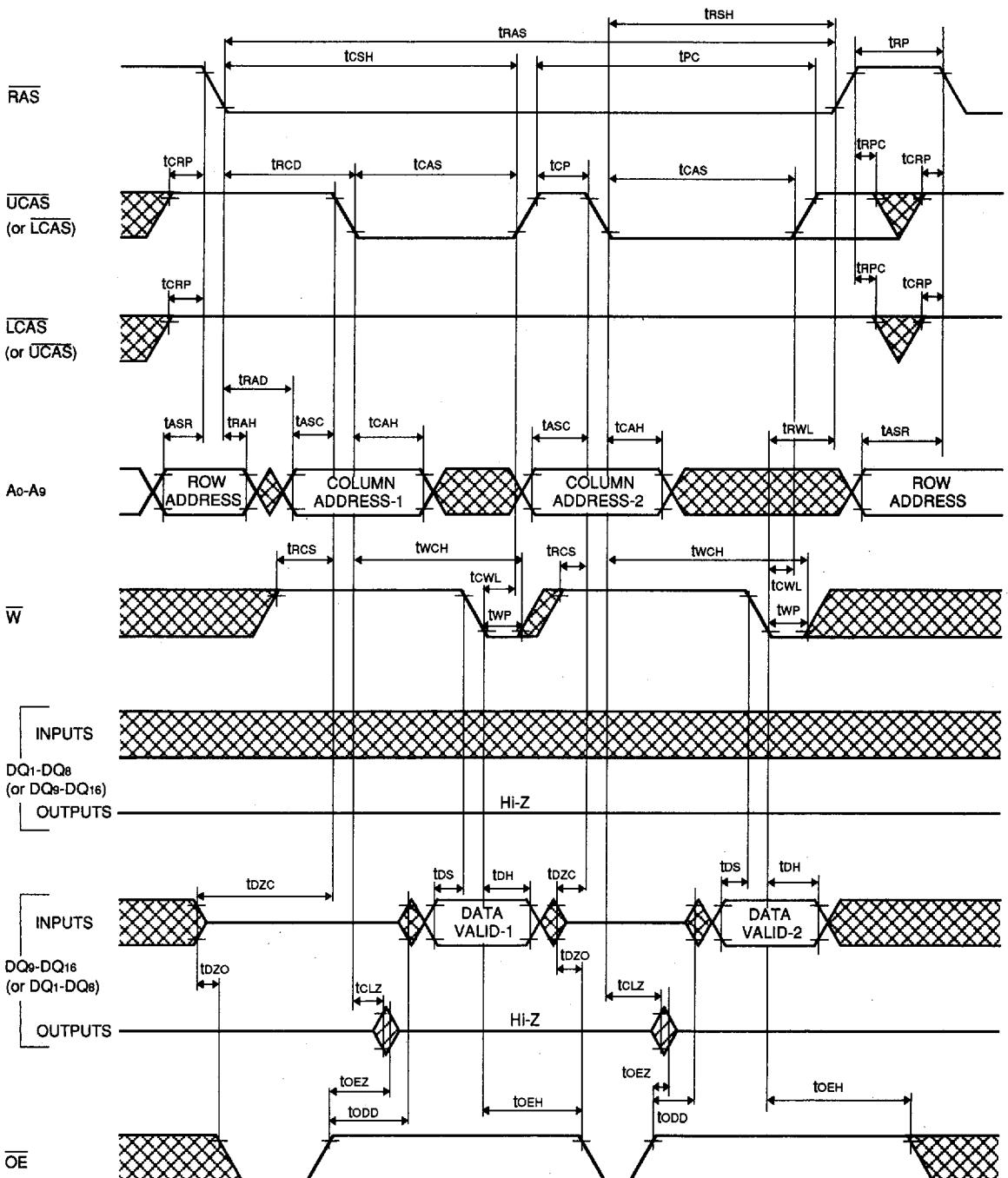


Fast Page Mode Write Cycle (Delayed Write)



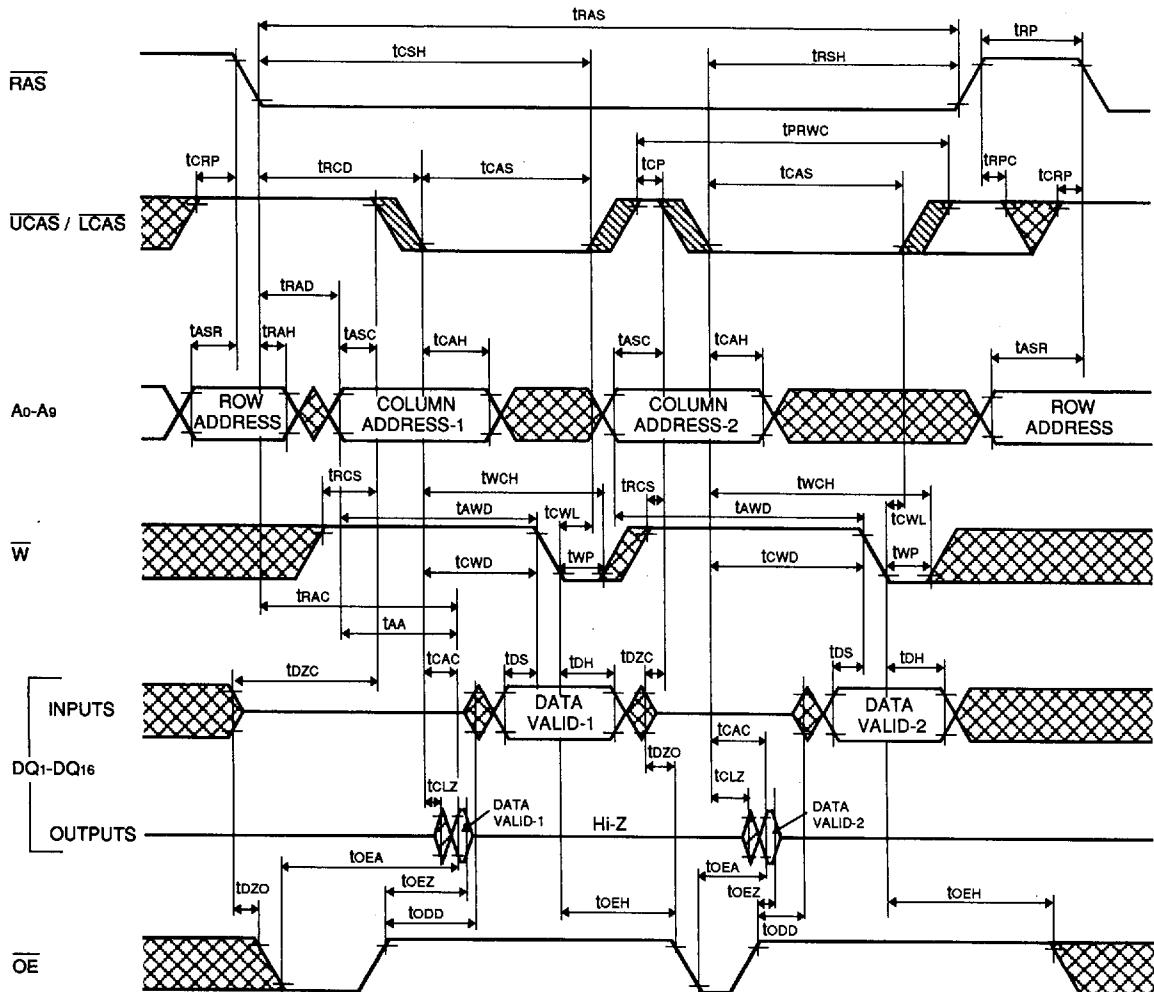
■ 6249825 0028765 2T2 ■

Fast Page Mode Upper / (Lower) Byte Write (Delayed Write)

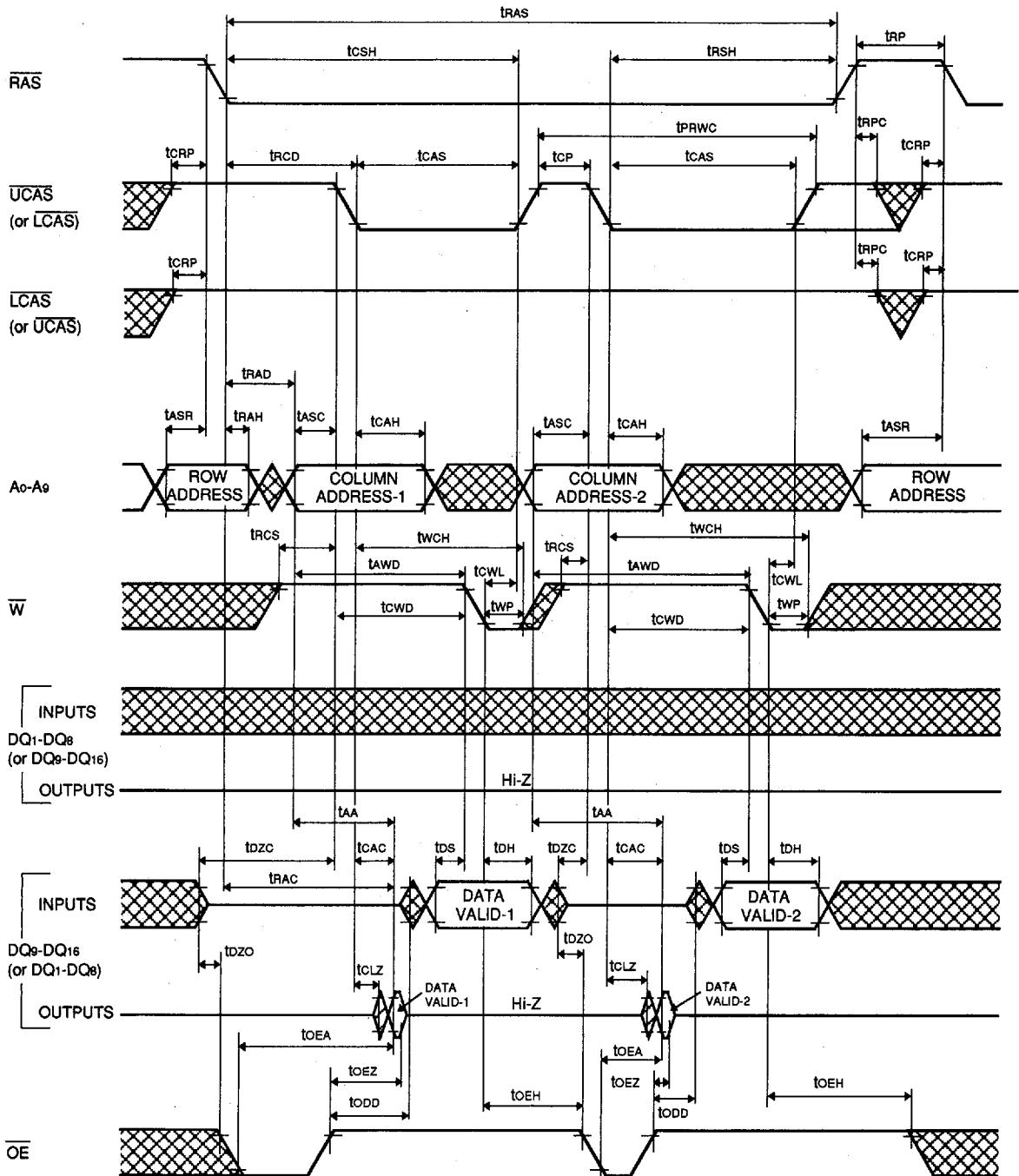


■ 6249825 0028766 139 ■

Fast Page Mode Read-Write, Read-Modify-Write Cycle



■ 6249825 0028767 075 ■

Fast Page Mode Read-Upper/(Lower) Write, Read-Modify-Upper/(Lower) Write Cycle

■ 6249825 0028768 T01 ■

SELF REFRESH SPECIFICATIONS

Self refresh devices are denoted by "S" after speed item, like -6S / -7S. The other characteristics and requirements than the below are same as normal devices.

ELECTRICAL CHARACTERISTICS (Ta=0~70°C, Vcc=5V ±10%, Vss=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
I _{CCA}	Supply current from Vcc Extended refresh cycle	M5M418160B -6S,-7S	RAS cycling CAS ≤ 0.2V or CAS before RAS refresh cycling W ≤ 0.2V or ≥ Vcc - 0.2V OE ≤ 0.2V or ≥ Vcc - 0.2V A ₀ ~A ₉ ≤ 0.2V or ≥ Vcc - 0.2V DQ = open t _{REF} = 128ms t _{RAS} = t _{REF} min~1 μs		500	μA
I _{CCA (AV)}	Average supply current from Vcc Self-Refresh cycle	M5M418160B -6S,-7S	RAS = CAS ≤ 0.2V		400	μA

TIMING REQUIREMENTS (Ta=0~70°C, Vcc=5V ±10%, Vss=0V, unless otherwise noted See notes 13,14)

Symbol	Parameter	Limits				Unit	
		M5M418160B-6S		M5M418160B-7S			
		Min	Max	Min	Max		
t _{RASS}	Self Refresh RAS low pulse width	100		100		μs	
t _{RPS}	Self Refresh RAS high precharge time	90		110		ns	
t _{CHS}	Self Refresh RAS hold time	-50		-50		ns	

SELF REFRESH ENTRY & EXIT CONDITIONS

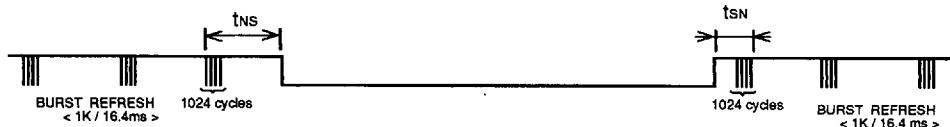
(1) In case of distributed refresh

The last / first full refresh cycles (1K) must be made within t_{NS} / t_{SN} before / after self refresh , on the condition of t_{NS} ≤ 16.4 ms and t_{SN} ≤ 16.4 ms.

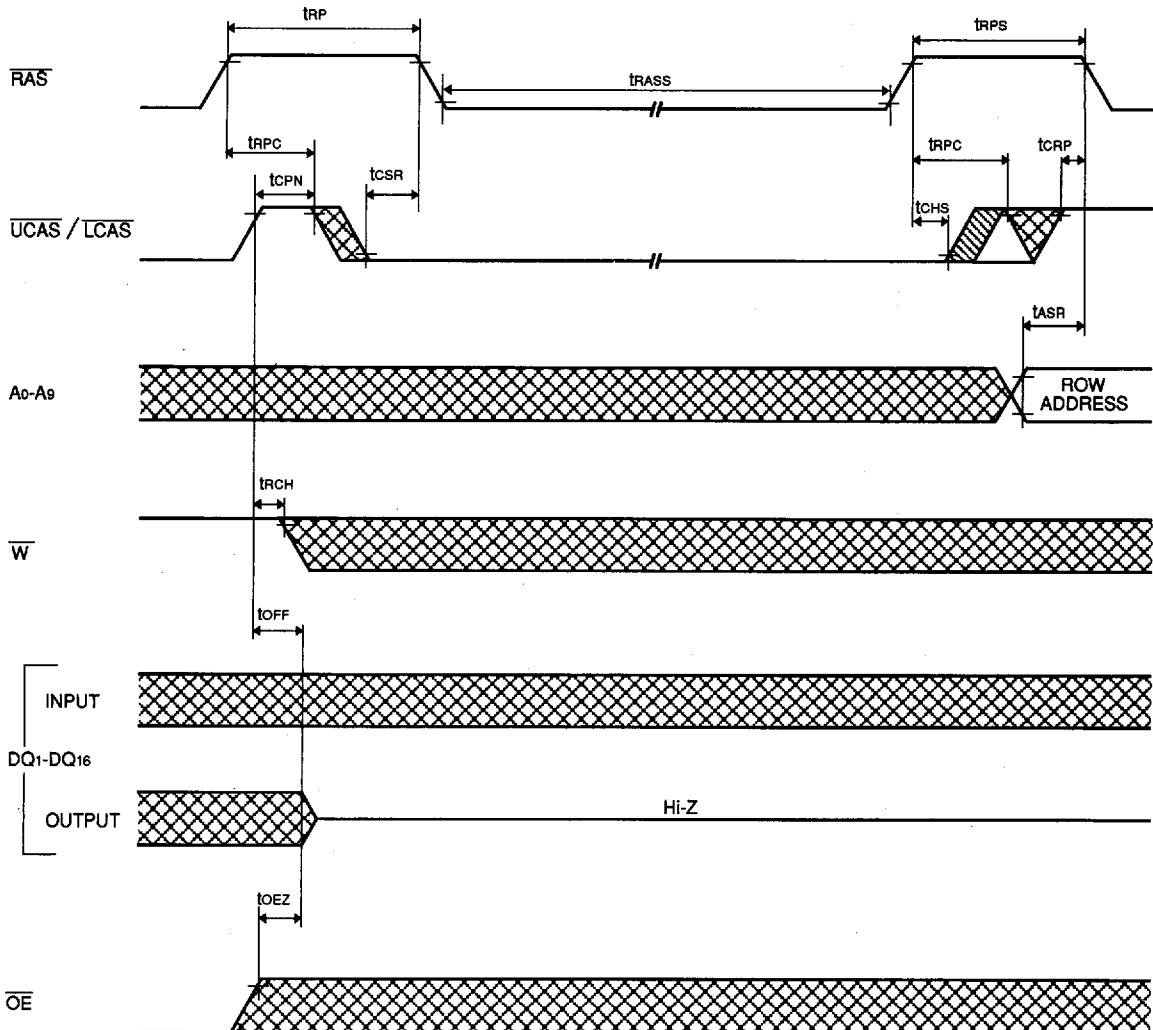


(2) In case of burst refresh

The last / first full refresh cycles (1K) must be made within t_{NS} / t_{SN} before / after self refresh , on the condition of t_{NS} + t_{SN} ≤ 16.4 ms.

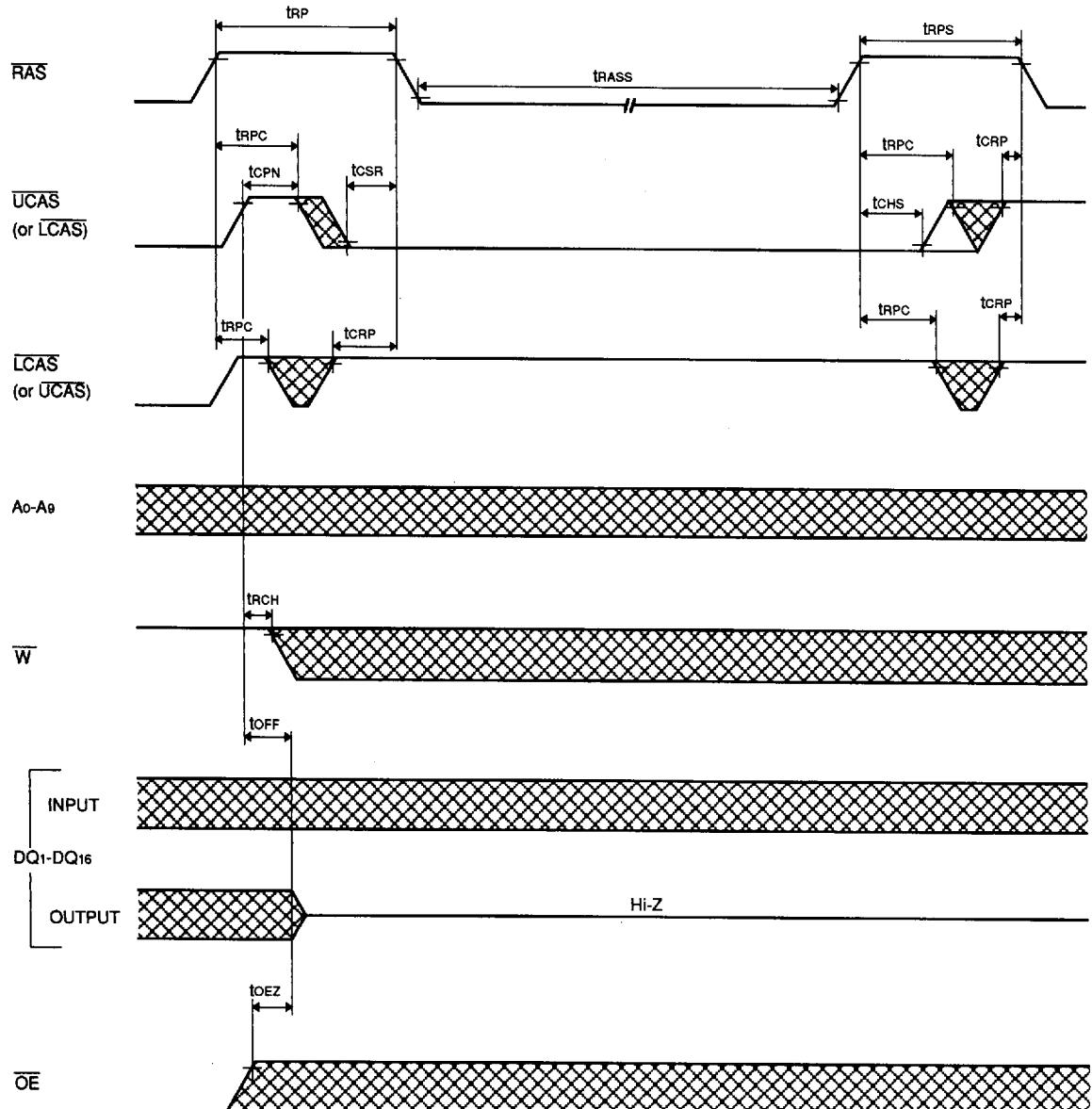


Self Refresh Cycle



■ 6249825 0028770 66T ■

Upper/(Lower) Self Refresh Cycle*



6249825 0028771 5Tb